

Ching Ping Wong

List of Publications by Year in descending order

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1,053
papers

51,277
citations

764

119
h-index

3312

184
g-index

1056
all docs

1056
docs citations

1056
times ranked

40850
citing authors

#	ARTICLE	IF	CITATIONS
1	Low-Cost High-Performance Solid-State Asymmetric Supercapacitors Based on MnO ₂ Nanowires and Fe ₂ O ₃ Nanotubes. <i>Nano Letters</i> , 2014, 14, 731-736.	4.5	1,035
2	Facile Synthesis of Nitrogen-Doped Graphene via Pyrolysis of Graphene Oxide and Urea, and its Electrocatalytic Activity toward the Oxygen-Reduction Reaction. <i>Advanced Energy Materials</i> , 2012, 2, 884-888.	10.2	840
3	Hydrogenated ZnO Core-Shell Nanocables for Flexible Supercapacitors and Self-Powered Systems. <i>ACS Nano</i> , 2013, 7, 2617-2626.	7.3	781
4	Thermal conductivity, elastic modulus, and coefficient of thermal expansion of polymer composites filled with ceramic particles for electronic packaging. <i>Journal of Applied Polymer Science</i> , 1999, 74, 3396-3403.	1.3	605
5	Recent advances of conductive adhesives as a lead-free alternative in electronic packaging: Materials, processing, reliability and applications. <i>Materials Science and Engineering Reports</i> , 2006, 51, 1-35.	14.8	593
6	Graphene-based nitrogen self-doped hierarchical porous carbon aerogels derived from chitosan for high performance supercapacitors. <i>Nano Energy</i> , 2015, 15, 9-23.	8.2	531
7	Ice-Templated Assembly Strategy to Construct 3D Boron Nitride Nanosheet Networks in Polymer Composites for Thermal Conductivity Improvement. <i>Small</i> , 2015, 11, 6205-6213.	5.2	473
8	MATERIALS SCIENCE: Electronics Without Lead. <i>Science</i> , 2005, 308, 1419-1420.	6.0	451
9	A Combination of Boron Nitride Nanotubes and Cellulose Nanofibers for the Preparation of a Nanocomposite with High Thermal Conductivity. <i>ACS Nano</i> , 2017, 11, 5167-5178.	7.3	407
10	Magnetic Alignment of Hexagonal Boron Nitride Platelets in Polymer Matrix: Toward High Performance Anisotropic Polymer Composites for Electronic Encapsulation. <i>ACS Applied Materials & Interfaces</i> , 2013, 5, 7633-7640.	4.0	394
11	Polymer Composite with Improved Thermal Conductivity by Constructing a Hierarchically Ordered Three-Dimensional Interconnected Network of BN. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 13544-13553.	4.0	394
12	3D Nitrogen-doped graphene prepared by pyrolysis of graphene oxide with polypyrrole for electrocatalysis of oxygen reduction reaction. <i>Nano Energy</i> , 2013, 2, 241-248.	8.2	367
13	Recent Advancements in Flexible and Stretchable Electrodes for Electromechanical Sensors: Strategies, Materials, and Features. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 12147-12164.	4.0	359
14	Large-scale production of two-dimensional nanosheets. <i>Journal of Materials Chemistry</i> , 2012, 22, 13494.	6.7	351
15	Thermal behavior of silver nanoparticles for low-temperature interconnect applications. <i>Journal of Electronic Materials</i> , 2005, 34, 168-175.	1.0	344
16	A flexible, ultra-highly sensitive and stable capacitive pressure sensor with convex microarrays for motion and health monitoring. <i>Nano Energy</i> , 2020, 70, 104436.	8.2	344
17	Simple preparation of nanoporous few-layer nitrogen-doped graphene for use as an efficient electrocatalyst for oxygen reduction and oxygen evolution reactions. <i>Carbon</i> , 2013, 53, 130-136.	5.4	331
18	Vertically Aligned and Interconnected Graphene Networks for High Thermal Conductivity of Epoxy Composites with Ultralow Loading. <i>Chemistry of Materials</i> , 2016, 28, 6096-6104.	3.2	325

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19	Novel polymer-ceramic nanocomposite based on high dielectric constant epoxy formula for embedded capacitor application. <i>Journal of Applied Polymer Science</i> , 2002, 83, 1084-1090.	1.3	323
20	Glass transition and relaxation behavior of epoxy nanocomposites. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , 2004, 42, 3849-3858.	2.4	318
21	Anticorrosive, Ultralight, and Flexible Carbon-Wrapped Metallic Nanowire Hybrid Sponges for Highly Efficient Electromagnetic Interference Shielding. <i>Small</i> , 2018, 14, e1800534.	5.2	310
22	Superior Capacitance of Functionalized Graphene. <i>Journal of Physical Chemistry C</i> , 2011, 115, 7120-7125.	1.5	307
23	Silver Nanowires: From Scalable Synthesis to Recyclable Foldable Electronics. <i>Advanced Materials</i> , 2011, 23, 3052-3056.	11.1	297
24	Construction of 3D Skeleton for Polymer Composites Achieving a High Thermal Conductivity. <i>Small</i> , 2018, 14, e1704044.	5.2	295
25	Hierarchical Silicon Etched Structures for Controlled Hydrophobicity/Superhydrophobicity. <i>Nano Letters</i> , 2007, 7, 3388-3393.	4.5	290
26	Nitrogen-doped hierarchically porous carbon foam: A free-standing electrode and mechanical support for high-performance supercapacitors. <i>Nano Energy</i> , 2016, 25, 193-202.	8.2	287
27	A Three-Dimensional Vertically Aligned Functionalized Multilayer Graphene Architecture: An Approach for Graphene-Based Thermal Interfacial Materials. <i>ACS Nano</i> , 2011, 5, 2392-2401.	7.3	283
28	High-Strength, Tough, Fatigue Resistant, and Self-Healing Hydrogel Based on Dual Physically Cross-Linked Network. <i>ACS Applied Materials & Interfaces</i> , 2016, 8, 24030-24037.	4.0	281
29	High-Concentration Aqueous Dispersions of MoS ₂ . <i>Advanced Functional Materials</i> , 2013, 23, 3577-3583.	7.8	271
30	A Novel Conformal RFID-Enabled Module Utilizing Inkjet-Printed Antennas and Carbon Nanotubes for Gas-Detection Applications. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2009, 8, 653-656.	2.4	267
31	Artificial nacre-like papers based on noncovalent functionalized boron nitride nanosheets with excellent mechanical and thermally conductive properties. <i>Nanoscale</i> , 2015, 7, 6774-6781.	2.8	265
32	Construction of a 3D-BaTiO ₃ network leading to significantly enhanced dielectric permittivity and energy storage density of polymer composites. <i>Energy and Environmental Science</i> , 2017, 10, 137-144.	15.6	265
33	Solvent-Assisted Thermal Reduction of Graphite Oxide. <i>Journal of Physical Chemistry C</i> , 2010, 114, 14819-14825.	1.5	264
34	Mechanical Chameleon through Dynamic Real-Time Plasmonic Tuning. <i>ACS Nano</i> , 2016, 10, 1788-1794.	7.3	262
35	Surface Functionalized Silver Nanoparticles for Ultrahigh Conductive Polymer Composites. <i>Chemistry of Materials</i> , 2006, 18, 2969-2973.	3.2	261
36	Facile preparation of nitrogen-doped graphene as a metal-free catalyst for oxygen reduction reaction. <i>Physical Chemistry Chemical Physics</i> , 2012, 14, 3381.	1.3	261

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37	Synthesis and dielectric properties of novel high-K polymer composites containing in-situ formed silver nanoparticles for embedded capacitor applications. <i>Journal of Materials Chemistry</i> , 2006, 16, 1543.	6.7	254
38	Amorphous nanostructured FeOOH and Co-Ni double hydroxides for high-performance aqueous asymmetric supercapacitors. <i>Nano Energy</i> , 2016, 21, 145-153.	8.2	254
39	Significant Enhancement of Thermal Conductivity in Bioinspired Freestanding Boron Nitride Papers Filled with Graphene Oxide. <i>Chemistry of Materials</i> , 2016, 28, 1049-1057.	3.2	250
40	Realizing an All-Around Hydrogel Electrolyte toward Environmentally Adaptive Dendrite-Free Aqueous Zn-MnO ₂ Batteries. <i>Advanced Materials</i> , 2021, 33, e2007559.	11.1	250
41	Scalable fabrication of MnO ₂ nanostructure deposited on free-standing Ni nanocone arrays for ultrathin, flexible, high-performance micro-supercapacitor. <i>Energy and Environmental Science</i> , 2014, 7, 2652-2659.	15.6	247
42	Highly Sensitive Flexible Pressure Sensor Based on Silver Nanowires-Embedded Polydimethylsiloxane Electrode with Microarray Structure. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 26314-26324.	4.0	234
43	Interstitial Occupancy by Extrinsic Alkali Cations in Perovskites and Its Impact on Ion Migration. <i>Advanced Materials</i> , 2018, 30, e1707350.	11.1	233
44	Low-loss percolative dielectric composite. <i>Applied Physics Letters</i> , 2005, 87, 082907.	1.5	232
45	Ultralight, super-elastic and volume-preserving cellulose fiber/graphene aerogel for high-performance electromagnetic interference shielding. <i>Carbon</i> , 2017, 115, 629-639.	5.4	228
46	A precise numerical prediction of effective dielectric constant for polymer-ceramic composite based on effective-medium theory. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2000, 23, 680-683.	1.4	223
47	Study on mono-dispersed nano-size silica by surface modification for underfill applications. <i>Journal of Colloid and Interface Science</i> , 2005, 292, 436-444.	5.0	220
48	Flexible Asymmetrical Solid-State Supercapacitors Based on Laboratory Filter Paper. <i>ACS Nano</i> , 2016, 10, 1273-1282.	7.3	215
49	Metal-Level Thermally Conductive yet Soft Graphene Thermal Interface Materials. <i>ACS Nano</i> , 2019, 13, 11561-11571.	7.3	214
50	Hollow-Structured Graphene-Silicone Composite-Based Piezoresistive Sensors: Decoupled Property Tuning and Bending Reliability. <i>Advanced Materials</i> , 2017, 29, 1702675.	11.1	213
51	Mechanically robust superhydrophobicity on hierarchically structured Si surfaces. <i>Nanotechnology</i> , 2010, 21, 155705.	1.3	211
52	Rational Design of Nickel Hydroxide-Based Nanocrystals on Graphene for Ultrafast Energy Storage. <i>Advanced Energy Materials</i> , 2018, 8, 1702247.	10.2	211
53	Cotton-derived cellulose film as a dendrite-inhibiting separator to stabilize the zinc metal anode of aqueous zinc ion batteries. <i>Energy Storage Materials</i> , 2022, 44, 57-65.	9.5	211
54	Superhydrophobicity on Two-Tier Rough Surfaces Fabricated by Controlled Growth of Aligned Carbon Nanotube Arrays Coated with Fluorocarbon. <i>Langmuir</i> , 2005, 21, 11208-11212.	1.6	207

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55	Material characterization of a high-dielectric-constant polymer-ceramic composite for embedded capacitor for RF applications. <i>Journal of Applied Polymer Science</i> , 2004, 92, 2228-2231.	1.3	201
56	Amorphous Ni(OH) ₂ encounter with crystalline CuS in hollow spheres: A mesoporous nano-shelled heterostructure for hydrogen evolution electrocatalysis. <i>Nano Energy</i> , 2018, 44, 7-14.	8.2	201
57	Through-plane assembly of carbon fibers into 3D skeleton achieving enhanced thermal conductivity of a thermal interface material. <i>Chemical Engineering Journal</i> , 2020, 380, 122550.	6.6	201
58	Flexible and Highly Sensitive Pressure Sensor Based on Microdome-Patterned PDMS Forming with Assistance of Colloid Self-Assembly and Replica Technique for Wearable Electronics. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 35968-35976.	4.0	200
59	Polymer composite with enhanced thermal conductivity and mechanical strength through orientation manipulating of BN. <i>Composites Science and Technology</i> , 2018, 160, 127-137.	3.8	199
60	High dielectric constant polyaniline/epoxy composites via in situ polymerization for embedded capacitor applications. <i>Polymer</i> , 2007, 48, 1510-1516.	1.8	196
61	Anti-freezing flexible aqueous Zn ²⁺ /MnO ₂ batteries working at ~35 °C enabled by a borax-crosslinked polyvinyl alcohol/glycerol gel electrolyte. <i>Journal of Materials Chemistry A</i> , 2020, 8, 6828-6841.	5.2	196
62	Graphene paper for exceptional EMI shielding performance using large-sized graphene oxide sheets and doping strategy. <i>Carbon</i> , 2017, 122, 74-81.	5.4	195
63	Ultrahigh-Aspect-Ratio Boron Nitride Nanosheets Leading to Superhigh In-Plane Thermal Conductivity of Foldable Heat Spreader. <i>ACS Nano</i> , 2021, 15, 6489-6498.	7.3	191
64	An ultrafast, high capacity and superior longevity Ni/Zn battery constructed on nickel nanowire array film. <i>Nano Energy</i> , 2016, 30, 900-908.	8.2	188
65	Benzylamine-treated Wide-Bandgap Perovskite with High Thermal Photostability and Photovoltaic Performance. <i>Advanced Energy Materials</i> , 2017, 7, 1701048.	10.2	188
66	Recent Advances in Flip-Chip Underfill: Materials, Process, and Reliability. <i>IEEE Transactions on Advanced Packaging</i> , 2004, 27, 515-524.	1.7	184
67	Silver Nanoparticle-Deposited Boron Nitride Nanosheets as Fillers for Polymeric Composites with High Thermal Conductivity. <i>Scientific Reports</i> , 2016, 6, 19394.	1.6	184
68	Vertically Aligned and Interconnected SiC Nanowire Networks Leading to Significantly Enhanced Thermal Conductivity of Polymer Composites. <i>ACS Applied Materials & Interfaces</i> , 2018, 10, 9669-9678.	4.0	183
69	High-performance flexible and self-healable quasi-solid-state zinc-ion hybrid supercapacitor based on borax-crosslinked polyvinyl alcohol/nanocellulose hydrogel electrolyte. <i>Journal of Materials Chemistry A</i> , 2019, 7, 26524-26532.	5.2	183
70	Facile Fabrication of Superhydrophobic Octadecylamine-Functionalized Graphite Oxide Film. <i>Langmuir</i> , 2010, 26, 16110-16114.	1.6	180
71	A Combined Process of In Situ Functionalization and Microwave Treatment to Achieve Ultrasmall Thermal Expansion of Aligned Carbon Nanotube-Polymer Nanocomposites: Toward Applications as Thermal Interface Materials. <i>Advanced Materials</i> , 2009, 21, 2421-2424.	11.1	178
72	Well-Aligned Open-Ended Carbon Nanotube Architectures: An Approach for Device Assembly. <i>Nano Letters</i> , 2006, 6, 243-247.	4.5	177

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73	Highly Stretchable and Sensitive Strain Sensor Based on Facilely Prepared Three-Dimensional Graphene Foam Composite. <i>ACS Applied Materials & Interfaces</i> , 2016, 8, 18954-18961.	4.0	176
74	Size-dependent melting properties of tin nanoparticles. <i>Chemical Physics Letters</i> , 2006, 429, 492-496.	1.2	175
75	An Ultralong, Highly Oriented Nickel Nanowire Array Electrode Scaffold for High-Performance Compressible Pseudocapacitors. <i>Advanced Materials</i> , 2016, 28, 4105-4110.	11.1	171
76	Covalent polymer functionalization of graphene for improved dielectric properties and thermal stability of epoxy composites. <i>Composites Science and Technology</i> , 2016, 122, 27-35.	3.8	171
77	Influence of interphase and moisture on the dielectric spectroscopy of epoxy/silica composites. <i>Polymer</i> , 2005, 46, 2297-2305.	1.8	169
78	A hybrid energy cell for self-powered water splitting. <i>Energy and Environmental Science</i> , 2013, 6, 2429.	15.6	162
79	Ultrathin Densified Carbon Nanotube Film with Metal-like Conductivity, Superior Mechanical Strength, and Ultrahigh Electromagnetic Interference Shielding Effectiveness. <i>ACS Nano</i> , 2020, 14, 14134-14145.	7.3	162
80	3D porous graphene with ultrahigh surface area for microscale capacitive deionization. <i>Nano Energy</i> , 2015, 11, 711-718.	8.2	161
81	A highly sensitive and flexible capacitive pressure sensor based on a micro-arrayed polydimethylsiloxane dielectric layer. <i>Journal of Materials Chemistry C</i> , 2018, 6, 13232-13240.	2.7	160
82	Learning from Natural Nacre: Constructing Layered Polymer Composites with High Thermal Conductivity. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 33001-33010.	4.0	159
83	A review of gassing behavior in $\text{Li}_{4}\text{Ti}_{5}\text{O}_{12}$ -based lithium ion batteries. <i>Journal of Materials Chemistry A</i> , 2017, 5, 6368-6381.	5.2	157
84	Water-dispersible graphene/polyaniline composites for flexible micro-supercapacitors with high energy densities. <i>Nano Energy</i> , 2015, 16, 470-478.	8.2	151
85	Recent advances in high-k nanocomposite materials for embedded capacitor applications. <i>IEEE Transactions on Dielectrics and Electrical Insulation</i> , 2008, 15, 1322-1328.	1.8	150
86	Preparation of highly conductive polymer nanocomposites by low temperature sintering of silver nanoparticles. <i>Journal of Materials Chemistry</i> , 2010, 20, 2018.	6.7	150
87	Review of Recent Advances in Electrically Conductive Adhesive Materials and Technologies in Electronic Packaging. <i>Journal of Adhesion Science and Technology</i> , 2008, 22, 1593-1630.	1.4	149
88	NaCl-templated synthesis of hierarchical porous carbon with extremely large specific surface area and improved graphitization degree for high energy density lithium ion capacitors. <i>Journal of Materials Chemistry A</i> , 2018, 6, 17057-17066.	5.2	149
89	A universal method for large-yield and high-concentration exfoliation of two-dimensional hexagonal boron nitride nanosheets. <i>Materials Today</i> , 2019, 27, 33-42.	8.3	149
90	Highly Conductive, Flexible, Polyurethane-Based Adhesives for Flexible and Printed Electronics. <i>Advanced Functional Materials</i> , 2013, 23, 1459-1465.	7.8	148

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91	Enhancing the Electrical and Optoelectronic Performance of Nanobelt Devices by Molecular Surface Functionalization. <i>Nano Letters</i> , 2007, 7, 1323-1328.	4.5	147
92	Highly Thermally Conductive Composite Papers Prepared Based on the Thought of Bioinspired Engineering. <i>ACS Applied Materials & Interfaces</i> , 2016, 8, 15645-15653.	4.0	145
93	Mechanistic investigation of the graphene functionalization using p-phenylenediamine and its application for supercapacitors. <i>Nano Energy</i> , 2015, 17, 160-170.	8.2	143
94	Integrated paper electrodes derived from cotton stalks for high-performance flexible supercapacitors. <i>Nano Energy</i> , 2018, 53, 337-344.	8.2	143
95	Spray-assisted assembled spherical boron nitride as fillers for polymers with enhanced thermally conductivity. <i>Chemical Engineering Journal</i> , 2019, 370, 166-175.	6.6	141
96	UV and thermally stable superhydrophobic coatings from sol-gel processing. <i>Journal of Colloid and Interface Science</i> , 2008, 326, 465-470.	5.0	140
97	Graphene oxide nano-sheets wrapped Cu ₂ O microspheres as improved performance anode materials for lithium ion batteries. <i>Nano Energy</i> , 2015, 11, 38-47.	8.2	139
98	Interfacial Engineering of Silicon Carbide Nanowire/Cellulose Microcrystal Paper toward High Thermal Conductivity. <i>ACS Applied Materials & Interfaces</i> , 2016, 8, 31248-31255.	4.0	139
99	Effect of Catalyst Shape and Etchant Composition on Etching Direction in Metal-Assisted Chemical Etching of Silicon to Fabricate 3D Nanostructures. <i>ACS Nano</i> , 2009, 3, 4033-4042.	7.3	137
100	In situ polymerization of mechanically reinforced, thermally healable graphene oxide/polyurethane composites based on Diels-Alder chemistry. <i>Journal of Materials Chemistry A</i> , 2014, 2, 20642-20649.	5.2	137
101	Future paper based printed circuit boards for green electronics: fabrication and life cycle assessment. <i>Energy and Environmental Science</i> , 2014, 7, 3674-3682.	15.6	136
102	Laser-processed graphene based micro-supercapacitors for ultrathin, rollable, compact and designable energy storage components. <i>Nano Energy</i> , 2016, 26, 276-285.	8.2	135
103	Lanthanide porphyrin complexes. Potential new class of nuclear magnetic resonance dipolar probe. <i>Journal of the American Chemical Society</i> , 1974, 96, 7149-7150.	6.6	134
104	Tunable electromagnetic properties and enhanced microwave absorption ability of flaky graphite/cobalt zinc ferrite composites. <i>Journal of Alloys and Compounds</i> , 2016, 662, 409-414.	2.8	134
105	Facile Preparation of Superelastic and Ultralow Dielectric Boron Nitride Nanosheet Aerogels via Freeze-Casting Process. <i>Chemistry of Materials</i> , 2015, 27, 5849-5855.	3.2	133
106	Wafer bonding using microwave heating of parylene intermediate layers. <i>Journal of Micromechanics and Microengineering</i> , 2004, 14, 625-631.	1.5	132
107	Core-shell SiO ₂ @RGO hybrids for epoxy composites with low percolation threshold and enhanced thermo-mechanical properties. <i>Journal of Materials Chemistry A</i> , 2014, 2, 18246-18255.	5.2	132
108	A Paper-Like Inorganic Thermal Interface Material Composed of Hierarchically Structured Graphene/Silicon Carbide Nanorods. <i>ACS Nano</i> , 2019, 13, 1547-1554.	7.3	131

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109	Relationship between Work of Adhesion and Contact Angle Hysteresis on Superhydrophobic Surfaces. <i>Journal of Physical Chemistry C</i> , 2008, 112, 11403-11407.	1.5	130
110	Fast Preparation of Printable Highly Conductive Polymer Nanocomposites by Thermal Decomposition of Silver Carboxylate and Sintering of Silver Nanoparticles. <i>ACS Applied Materials & Interfaces</i> , 2010, 2, 2637-2645.	4.0	130
111	Facile Preparation of Monodisperse, Impurity-Free, and Antioxidation Copper Nanoparticles on a Large Scale for Application in Conductive Ink. <i>ACS Applied Materials & Interfaces</i> , 2014, 6, 560-567.	4.0	129
112	Ultrafast, dry microwave synthesis of graphene sheets. <i>Journal of Materials Chemistry</i> , 2010, 20, 4781.	6.7	128
113	Hybridization of graphene nanosheets and carbon-coated hollow Fe ₃ O ₄ nanoparticles as a high-performance anode material for lithium-ion batteries. <i>Journal of Materials Chemistry A</i> , 2016, 4, 2453-2460.	5.2	128
114	<i>In situ</i> growth of Cu(OH) ₂ @FeOOH nanotube arrays on catalytically deposited Cu current collector patterns for high-performance flexible in-plane micro-sized energy storage devices. <i>Energy and Environmental Science</i> , 2019, 12, 194-205.	15.6	128
115	Shape-Tailorable Graphene-Based Ultra-High-Rate Supercapacitor for Wearable Electronics. <i>ACS Nano</i> , 2015, 9, 5636-5645.	7.3	127
116	Silicon-Based Hybrid Energy Cell for Self-Powered Electrodegradation and Personal Electronics. <i>ACS Nano</i> , 2013, 7, 2808-2813.	7.3	125
117	Systematic study on structural and electronic properties of diamine/triamine functionalized graphene networks for supercapacitor application. <i>Nano Energy</i> , 2017, 31, 183-193.	8.2	124
118	Pseudocapacitive anthraquinone modified with reduced graphene oxide for flexible symmetric all-solid-state supercapacitors. <i>Carbon</i> , 2018, 127, 459-468.	5.4	123
119	Growth and electrical characterization of high-aspect-ratio carbon nanotube arrays. <i>Carbon</i> , 2006, 44, 253-258.	5.4	121
120	Composition-tuned Wide Bandgap Perovskites: From Grain Engineering to Stability and Performance Improvement. <i>Advanced Functional Materials</i> , 2018, 28, 1803130.	7.8	121
121	Aligned Carbon Nanotube Stacks by Water-Assisted Selective Etching. <i>Nano Letters</i> , 2005, 5, 2641-2645.	4.5	120
122	Printed electrically conductive composites: conductive filler designs and surface engineering. <i>Journal of Materials Chemistry C</i> , 2013, 1, 4052.	2.7	120
123	Worm-like amorphous MnO ₂ nanowires grown on textiles for high-performance flexible supercapacitors. <i>Journal of Materials Chemistry A</i> , 2014, 2, 595-599.	5.2	120
124	Interfacial Laser-Induced Graphene Enabling High-Performance Liquid-Solid Triboelectric Nanogenerator. <i>Advanced Materials</i> , 2021, 33, e2104290.	11.1	120
125	Controlled Growth of Multilayer, Few-Layer, and Single-Layer Graphene on Metal Substrates. <i>Journal of Physical Chemistry C</i> , 2011, 115, 5232-5238.	1.5	119
126	Achieving Significant Thermal Conductivity Enhancement via an Ice-Templated and Sintered BN-SiC Skeleton. <i>ACS Applied Materials & Interfaces</i> , 2020, 12, 2892-2902.	4.0	118

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127	Ice-Templated MXene/Ag@Epoxy Nanocomposites as High-Performance Thermal Management Materials. ACS Applied Materials & Interfaces, 2020, 12, 24298-24307.	4.0	117
128	Template-grown graphene/porous Fe ₂ O ₃ nanocomposite: A high-performance anode material for pseudocapacitors. Nano Energy, 2015, 15, 719-728.	8.2	116
129	Syntheses and characterizations of thermally reworkable epoxy resins II. Journal of Polymer Science Part A, 2000, 38, 3771-3782.	2.5	115
130	Effects of shrinkage on conductivity of isotropic conductive adhesives. International Journal of Adhesion and Adhesives, 2000, 20, 189-193.	1.4	115
131	Synthesis and Thermal and Wetting Properties of Tin/Silver Alloy Nanoparticles for Low Melting Point Lead-Free Solders. Chemistry of Materials, 2007, 19, 4482-4485.	3.2	115
132	Enhanced thermal conductivity for Ag-deposited alumina sphere/epoxy resin composites through manipulating interfacial thermal resistance. Composites Part A: Applied Science and Manufacturing, 2018, 107, 561-569.	3.8	115
133	Highly Compressive Boron Nitride Nanotube Aerogels Reinforced with Reduced Graphene Oxide. ACS Nano, 2019, 13, 7402-7409.	7.3	115
134	Conductivity enhancement of nano silver-filled conductive adhesives by particle surface functionalization. Journal of Electronic Materials, 2005, 34, 1432-1439.	1.0	114
135	Silver/polymer nanocomposite as a high-k polymer matrix for dielectric composites with improved dielectric performance. Journal of Materials Chemistry, 2008, 18, 4821.	6.7	113
136	Triethanolamine functionalized graphene-based composites for high performance supercapacitors. Journal of Materials Chemistry A, 2015, 3, 21789-21796.	5.2	112
137	An improved methodology for determining temperature dependent moduli of underfill encapsulants. IEEE Transactions on Components and Packaging Technologies, 2000, 23, 434-439.	1.4	111
138	Flexible micro-supercapacitor based on in-situ assembled graphene on metal template at room temperature. Nano Energy, 2014, 10, 222-228.	8.2	111
139	Improving thermal conductivity through welding boron nitride nanosheets onto silver nanowires via silver nanoparticles. Composites Science and Technology, 2019, 177, 118-126.	3.8	111
140	Rational Design of a Printable, Highly Conductive Silicone-based Electrically Conductive Adhesive for Stretchable Radio Frequency Antennas. Advanced Functional Materials, 2015, 25, 464-470.	7.8	109
141	Facile preparation of nitrogen/sulfur co-doped and hierarchical porous graphene hydrogel for high-performance electrochemical capacitor. Journal of Power Sources, 2017, 345, 146-155.	4.0	109
142	Sea urchin-like microstructure pressure sensors with an ultra-broad range and high sensitivity. Nature Communications, 2021, 12, 1776.	5.8	109
143	Reversible Superhydrophobic to Superhydrophilic Transition of ZnO Nanorod/Epoxy Composite Films. ACS Applied Materials & Interfaces, 2012, 4, 3959-3964.	4.0	108
144	Porous octahedral PdCu nanocages as highly efficient electrocatalysts for the methanol oxidation reaction. Journal of Materials Chemistry A, 2018, 6, 3906-3912.	5.2	108

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145	Multiscale Structural Modulation of Anisotropic Graphene Framework for Polymer Composites Achieving Highly Efficient Thermal Energy Management. <i>Advanced Science</i> , 2021, 8, 2003734.	5.6	108
146	Variable Frequency Microwave Synthesis of Silver Nanoparticles. <i>Journal of Nanoparticle Research</i> , 2006, 8, 117-124.	0.8	106
147	Microstructure engineering of graphene towards highly thermal conductive composites. <i>Composites Part A: Applied Science and Manufacturing</i> , 2018, 112, 216-238.	3.8	106
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